

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "SN65HVD96D"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN65HVD96D	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	D 8	4.9x3.9x1.75	112.4

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.056437	99.998228	999982	0.050226	502
Precious Metals	Silver	7440-22-4	0.000001	0.001772	18	0.000001	0
Sub-Total			0.056438	100	1000000	0.050227	502
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.647009	80.000025	800000	0.57581	5758
Thermoplastics	Epoxy	85954-11-6	0.161752	19.999975	200000	0.143952	1440
Sub-Total			0.808761	100	1000000	0.719762	7198
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	49.93	99.86	998600	44.435532	444355
Copper and Its Alloys	Iron	7439-89-6	0.05	0.1	1000	0.044498	445
Copper and Its Alloys	Phosphorus	7723-14-0	0.02	0.04	400	0.017799	178
Sub-Total			50	100	1000000	44.497829	444978
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.38048	95.12	951200	0.338611	3386
Precious Metals	Gold	7440-57-5	0.00312	0.78	7800	0.002777	28
Precious Metals	Palladium	7440-05-3	0.0164	4.1	41000	0.014595	146
Sub-Total			0.4	100	1000000	0.355983	3560
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	51.441143	87.999999	880000	45.780384	457804
Other Plastics and Rubber	Carbon Black	1333-86-4	0.175368	0.300001	3000	0.15607	1561
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.321507	0.55	5500	0.286127	2861
Thermoplastics	Epoxy	85954-11-6	6.517827	11.15	111500	5.800583	58006
Sub-Total			58.455845	100	1000000	52.023164	520232
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.643988	100	1000000	2.353035	23530
Sub-Total			2.643988	100	1000000	2.353035	23530
Total			112.365032			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.